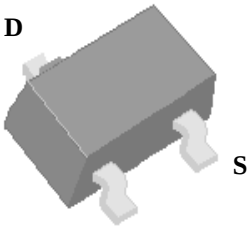
XPX1008AS

100V N-Channel Enhancement Mode MOSFET

Description

The XPX1008AS uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

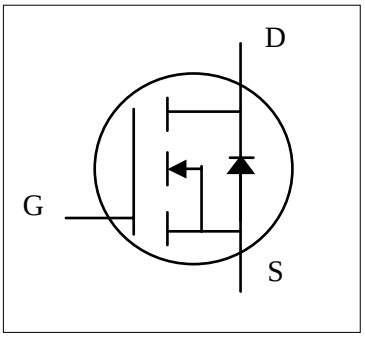


SOT23-3L

General Features

V_{DS} = 100V I_D =8A

$R_{DS(ON)}$ <80mΩ@ V_{GS}=10V



Application

Automative lighting

Load switch

PSE

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
XPX1008AS	SOT23-3L	1008	3000

Absolute Maximum Ratings (TC=25℃unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	100	V
VGS	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Drain Current, V_{GS} @ 10V	8	A
I_D@T_C=100℃	Drain Current, V_{GS} @ 10V	6.5	A
IDM	Pulsed Drain Current[1]	24	A
P_D@T_C=25℃	Total Power Dissipation	30	W
P_D@T_A=25℃	Total Power Dissipation[3]	2.7	W
TSTG	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃
RθJA	Maximum Thermal Resistance, Junctionambient	100	℃/W
RθJC	Maximum Thermal Resistance, Junction-case	5.1	℃/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	VGS=0V, ID=250μA	100	107	-	V
IDSS	Zero Gate Voltage Drain Current	VDS=100V, VGS=0V,	-	-	1.0	μA
IGSS	Gate to Body Leakage Current	VDS=0V, VGS=±20V	-	-	±100	nA
VGS(th)	Gate Threshold Voltage	VDS=VGS, ID=250μA	1.2	1.85	2.5	V
RDS(on)	Static Drain-Source on-Resistance note3	VGS=10V, ID=5A	-	80	100	mΩ
		VGS=4.5V, ID=3A	-	95	125	mΩ
g fs	Forward Transconductance	V DS =5V , I D =5A		14		S
RG	Gate Resistance	VDS = 0V, VGS =0V,f =1MHz		3		Ω
Ciss	Input Capacitance	VDS=15V, VGS=0V, f=1.0MHz	-	1100	-	pF
Coss	Output Capacitance		-	55	-	pF
Crss	Reverse Transfer Capacitance		-	40	-	pF
Qg	Total Gate Charge	VDS=50V, ID=5A, VGS=10V	-	11.9	-	nC
Qgs	Gate-Source Charge		-	2.8	-	nC
Qgd	Gate-Drain(“Miller”) Charge		-	1.7	-	nC
td(on)	Turn-on Delay Time	VDS=30V, ID=5A, RG=1.8Ω, VGS=10V	-	3.8	-	ns
tr	Turn-on Rise Time		-	25.8	-	ns
td(off)	Turn-off Delay Time		-	16	-	ns
tf	Turn-off Fall Time		-	8.8	-	ns
IS	Continuous Source Current1,5	VG=VD=0V , Force Current	-	-	14.6	A
ISM	Pulsed Source Current2,5		-	-	25	A
VSD	Diode Forward Voltage2	VGS=0V, IS=10A	-	-	1.2	V

Note :

1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.

2、The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%

3、The power dissipation is limited by 150℃ junction temperature

4、The data is theoretically the same as I D and I DM , in real applications , should be limited by total power dissipation.

Typical Characteristics

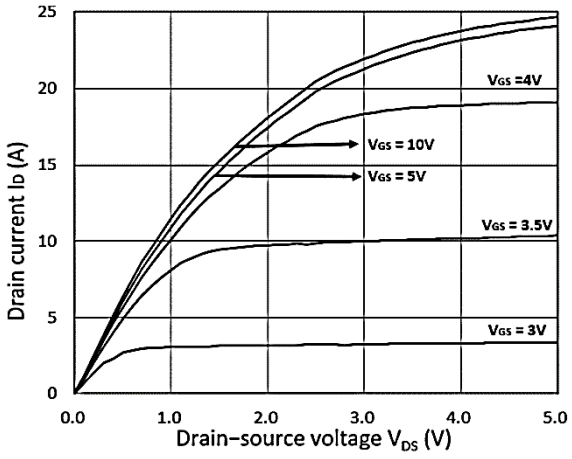


Figure 1. Output Characteristics

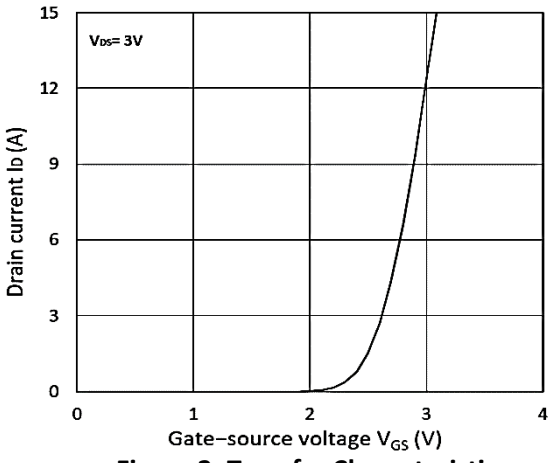


Figure 2. Transfer Characteristics

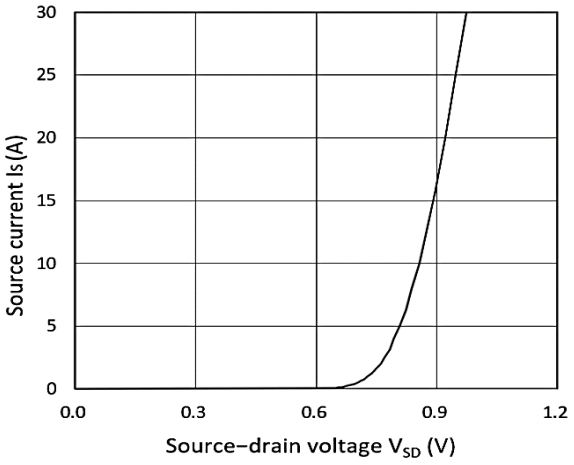


Figure 3. Forward Characteristics of Reverse

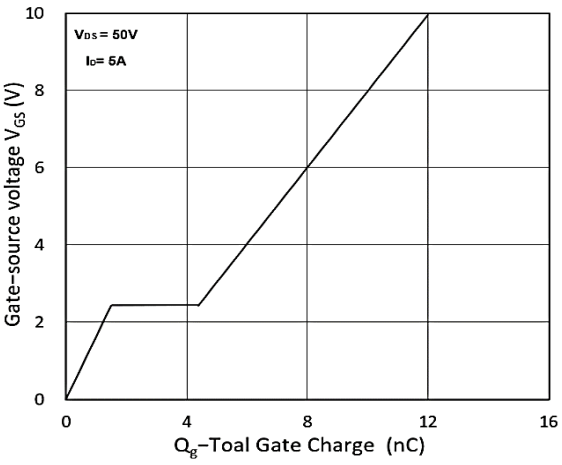


Figure 4. Gate Charge Characteristics

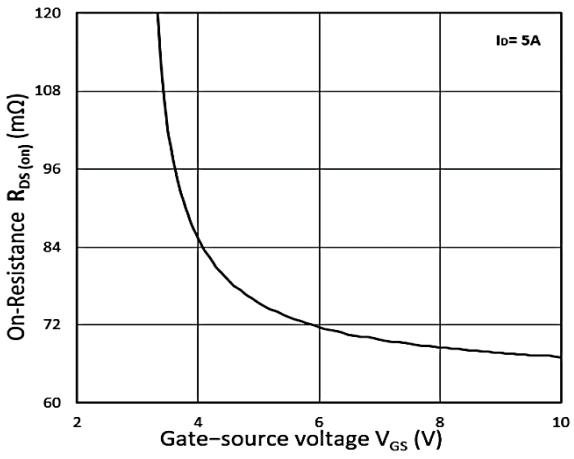


Figure 5. R DS(on) vs. V GS

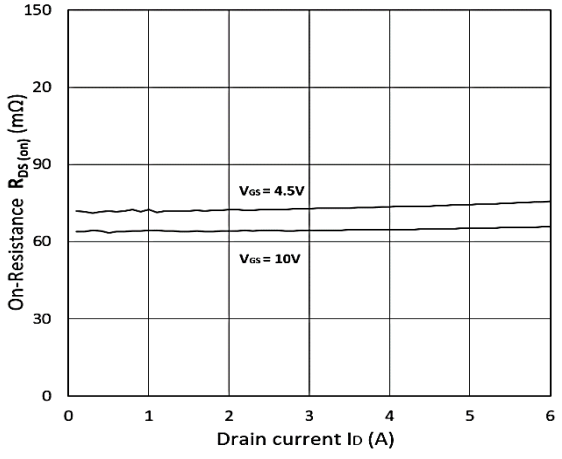


Figure 6. R DS(on) vs. ID

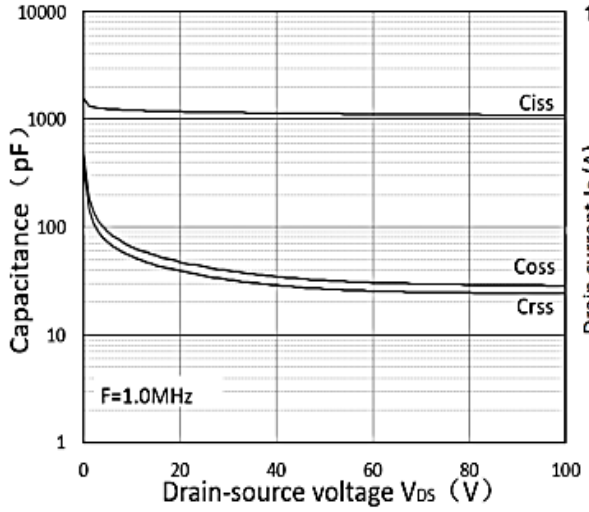


Figure 7. Capacitance Characteristics

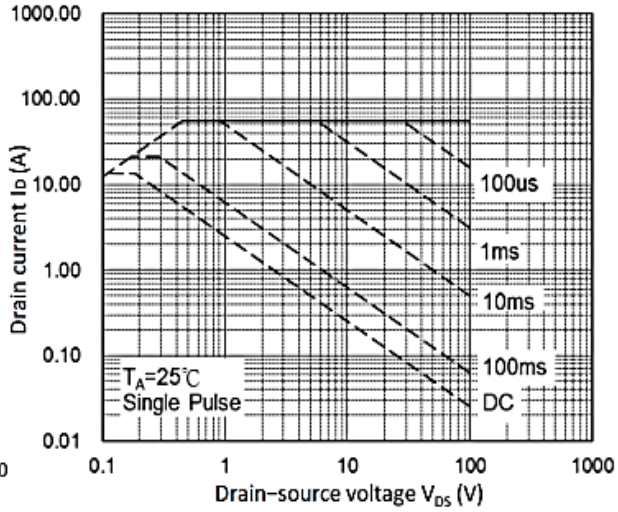


Figure 8. Safe Operating Area

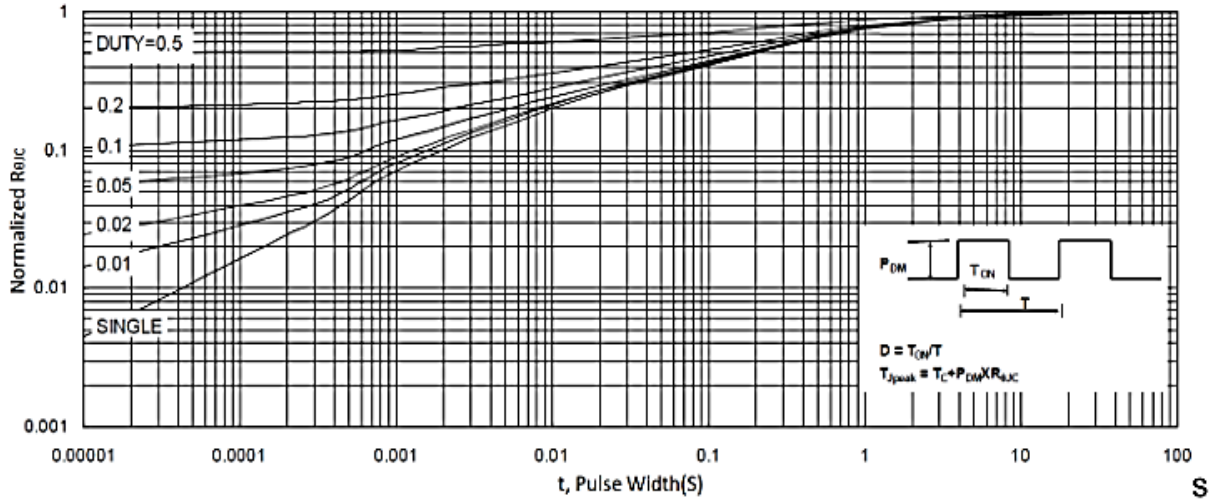
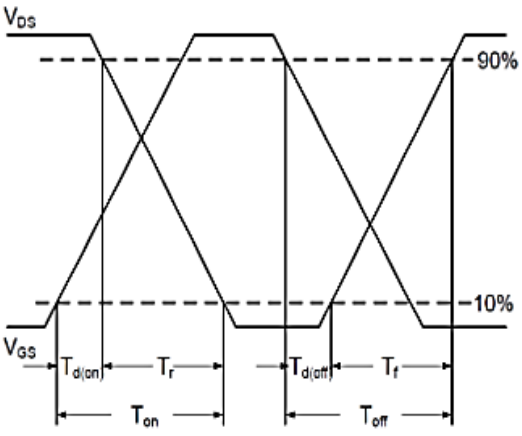
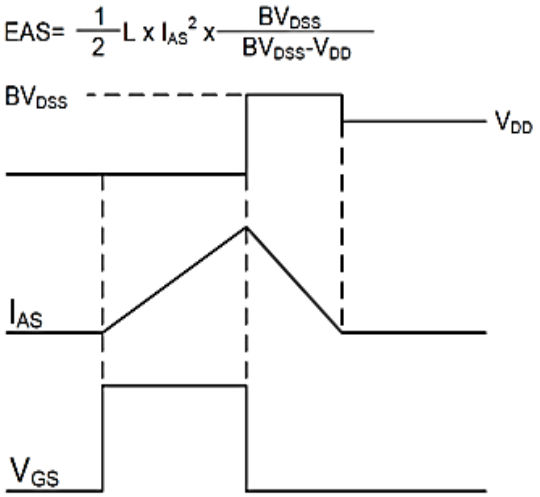
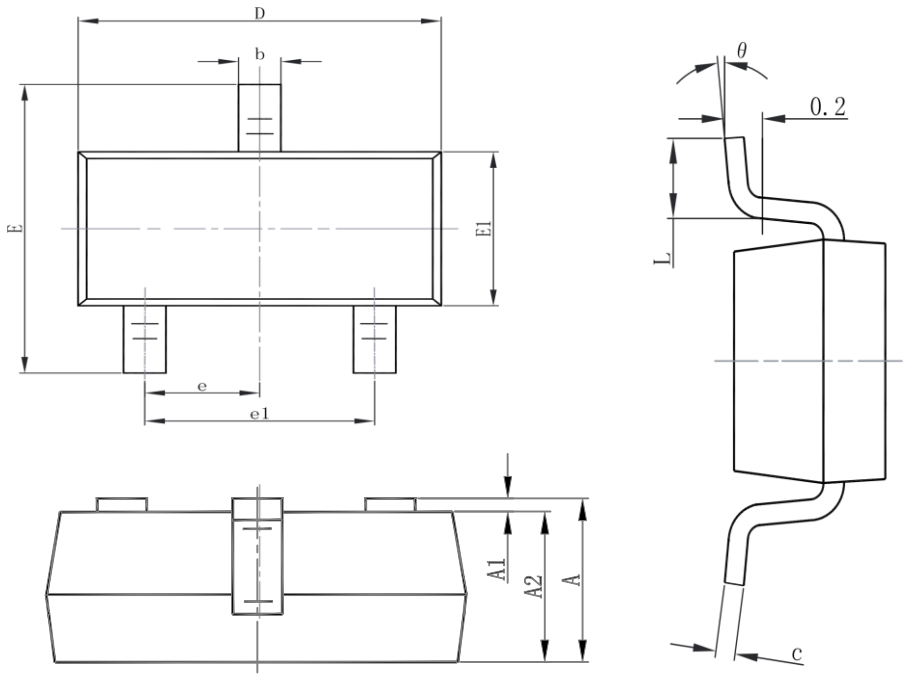


Figure 9. Normalized Maximum Transient Thermal Impedance





Package Mechanical Data-SOT23-3-SLS-Single



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Flow (wave) soldering (solder dipping)

Product	Peak Temperature	Dipping Time
Pb device	245℃±5℃	5sec±1sec
Pb-Free device	260℃+0/-5℃	5sec±1sec

This integrated circuit can be damaged by ESD UniverChip Corporation recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedure can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Attention:

- Any and all XPX power products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your XPX power representative nearest you before using any XPX power products described or contained herein in such applications.

- XPX power assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all XPX power products described or contained herein.

- Specifications of any and all XPX power products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

- XPX power Semiconductor CO.,LTD. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with some probability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits and error prevention circuits for safe design, redundant design, and structural design.

- In the event that any or all XPX power products(including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from the authorities concerned in accordance with the above law.

- No part of this publication may be reproduced or transmitted in any form or by any means, electronic or mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of XPX power Semiconductor CO.,LTD.

- Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. XPX power believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements of intellectual property rights or other rights of third parties.

- Any and all information described or contained herein are subject to change without notice due to product/ technology improvement, etc. When designing equipment, refer to the "Delivery Specification" for the XPX power product that you intend to use.

- This catalog provides information as of Sep.2019. Specifications and information herein are subject to change without notice.